

## CLAIM AMENDMENTS

All pending claims are reproduced below, with claims 1 and 6 being amended:

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1. (Currently Amended) A one system module in which a ceramic printed circuit board (PCB) and an epoxy PCB are disposed inside a module body, a power element and signal elements being respectively mounted on an upper portion of each PCB, the one system module further comprising:

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a module body, the module body including an inside surface having a first groove formed at a lower portion thereof and a second groove formed at a mid portion thereof, the second groove comprising a generally C-shaped recess having a bottom wall, a top wall parallel to the bottom wall, and a side wall interconnecting the top wall and the bottom wall, wherein the ceramic PCB is supported in the first groove so as to be disposed inside the module body, and the epoxy PCB is supported in the second groove by the bottom wall, the side wall, and the top wall so as to be disposed inside the module body;

at least one power pin mounted on the upper surface at least one edge of the ceramic PCB, the power pin being for receiving power from a source external to the module body; and

at least one signal pin embedded inside the module body and mounted on the upper surface at least one edge of the epoxy PCB, the signal pin being for receiving and/or transmitting various signals from/to elements external to the module body.

2. (Original) The one system module according to claim 1, wherein aluminum wire bonding is performed to mount elements on the ceramic PCB, while gold wire bonding is performed to mount a microcomputer on the epoxy PCB.

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amended.  
3. (Previously Presented) The one system module according to claim 1, wherein the at least one power pin is mounted on the ceramic PCB by soldering, while the at least one signal pin is mounted on the epoxy PCB by soldering.

4. (Cancelled)

5. (Previously Presented) The one system module according to claim 1, wherein the power pins are mounted on the upper portion edges of the ceramic PCB and the signal pins are mounted on the upper portion at least two opposed edges of the epoxy PCB in line with the power pins.

6. (Currently Amended) A one system module comprising:

a module body, said module body including an inside surface having a first groove formed at a lower portion thereof and a second groove formed at a mid portion thereof, the second groove comprising a generally C-shaped recess having a bottom wall, a top wall parallel to the bottom wall, and a side wall interconnecting the top wall and the bottom wall;

a ceramic printed circuit board (PCB) supported in said first groove so as to be disposed inside said module body, said ceramic PCB having power elements secured thereto;

an epoxy PCB supported in said second groove by the bottom wall, the side wall, and the top wall so as to be disposed inside said module body, said epoxy PCB having signal elements secured thereto;

32 part.  
a socket located between said ceramic PCB and said epoxy PCB, said socket establishing electrical communications between said power elements of said ceramic PCB and said signal elements of said epoxy PCB;

at least one power pin mounted on an upper surface and along a first edge of said ceramic PCB, said power pin being for receiving power from a source external to said module body; and

at least one signal pin mounted on an upper surface and along a first edge of said epoxy PCB, said signal pin being for receiving and/or transmitting various signals from/to elements external to said module body, wherein said signal pin is linearly arranged relative to said power pin.

7. (Previously Presented) The one system module according to claim 6, wherein said power pin is a first power pin and said signal pin is a first signal pin, and further comprising:

a second power pin mounted on said upper surface and along a second edge of said ceramic PCB, wherein said second edge of said ceramic PCB is opposite said first edge of said ceramic PCB; and

a second signal pin mounted on said upper surface and along a second edge of said epoxy PCB, wherein said second edge of said epoxy PCB is opposite said first edge of said epoxy PCB.

8. (Previously Presented) The one system module according to claim 7, wherein said second signal pin is linearly arranged relative to said second power pin.

9. (Previously Presented) The one system module according to claim 6, wherein said signal elements include a microprocessor.

10. (Previously Presented) The one system module according to claim 9, wherein gold wire bonding is used to secure leads of said microprocessor to said epoxy PCB, and wherein aluminum wire bonding is used secure leads of said power elements to said ceramic PCB.

11. (Previously Presented) The one system module according to claim 10, wherein said power pin is mounted on said ceramic PCB by soldering, and said signal pin is mounted on said epoxy PCB by soldering.

12. (Previously Presented) The one system module according to claim 6, wherein said power pin is mounted on said ceramic PCB by soldering; and said signal pin is mounted on said epoxy PCB by soldering.

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